

GP2S29

Long Focal Distance, Reflective Type Photointerrupter

■ Features

1. Wide range of detecting distance
(Detecting distance : 1 to 20mm)
2. Prism system
3. High sensitivity (S/N ratio : 75)
4. Easy circuit design in sub sequent stage due to large output current

■ Applications

1. Printers
2. Facsimiles
3. DAT
4. Copiers
5. LBP's

■ Absolute Maximum Ratings

(Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	*1 Forward current	I _F	50	mA
	*2 Peak forward current	I _{FM}	1	A
	Reverse voltage	V _R	6	V
Output	*1 Power dissipation	P	75	mW
	Collector-emitter voltage	V _{CEO}	35	V
	Emitter-collector voltage	V _{ECO}	6	V
	Collector current	I _{CP}	20	mA
	*1 Collector dissipation	P _C	75	mW
	*1 Total power dissipation	P _{tot}	100	mW
	Operating temperature	T _{opr}	-25 to +85	°C
	Storage temperature	T _{stg}	-40 to +100	°C
	*3 Soldering temperature	T _{sol}	260	°C

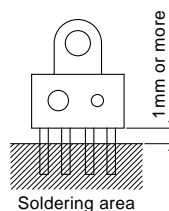
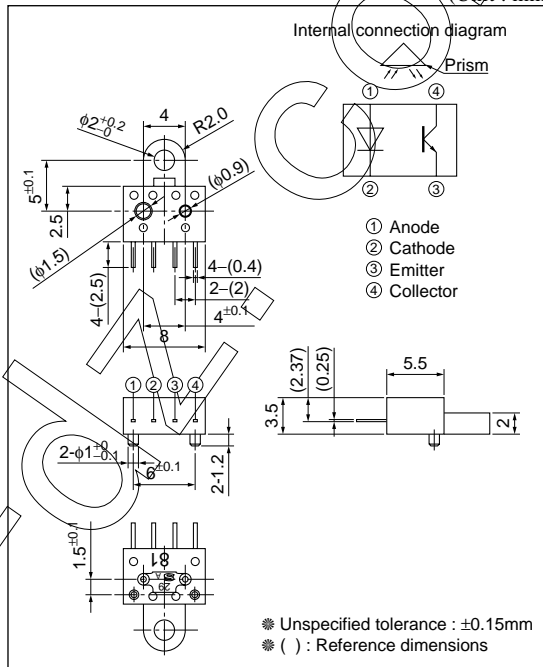
*1 The derating factors of absolute maximum ratings due to ambient temperature are shown in Fig.1 to 2

*2 Pulse width<=100μs, Duty ratio:0.01

*3 For 3s

■ Outline Dimensions

(Unit : mm)



■ Electro-optical Characteristics

(Ta=25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	V_F	$I_F=20\text{mA}$	—	1.25	1.4	V
	Peak forward voltage	V_{FM}	$I_{FM}=0.5\text{A}$	—	3	4	V
	Reverse current	I_R	$V_R=3\text{V}$	—	—	10	μA
Output	Collector dark current	I_{CEO}	$V_{CE}=20\text{V}$	—	—	100	nA
Transfer characteristics	*4 Collector current	I_C	$V_{CE}=5\text{V}, I_F=20\text{mA}$	0.2	—	2.4	mA
	*5 Leak current	I_{LEAK}	$V_{CE}=5\text{V}, I_F=20\text{mA}$	—	—	10	μA
	Signal to noise ratio		I_C/I_{LEAK}	75	—	—	—
	*4 Collector-emitter saturation voltage		$I_C=0.1\text{mA}$ $I_F=40\text{mA}$	—	0.1	0.4	V
	Response time	Rise time	$V_{CE}=2\text{V}, I_C=0.5\text{mA}$ $R_L=1\text{k}\Omega, d=8\text{mm}$	—	38	90	μs
		Fall time		—	48	110	μs

*4 Refer to Fig.13

*5 Refer to Fig.15

Fig.1 Forward Current vs. Ambient Temperature

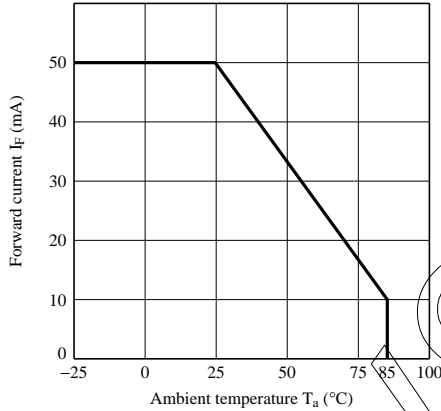


Fig.2 Power Dissipation vs. Ambient Temperature

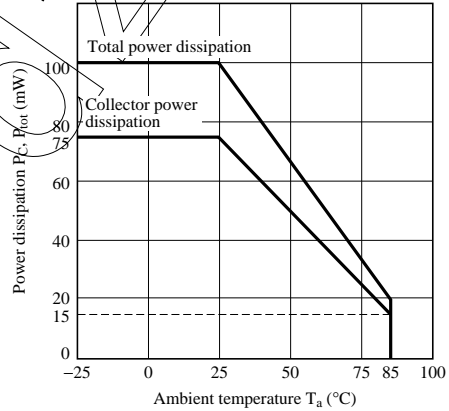


Fig.3 Peak Forward Current vs. Duty Ratio

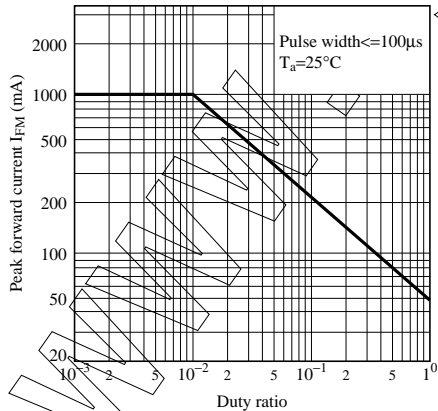


Fig.4 Forward Current vs. Forward Voltage

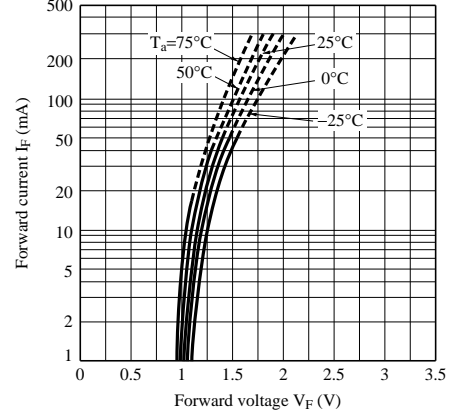


Fig.5 Collector Current vs. Forward Current

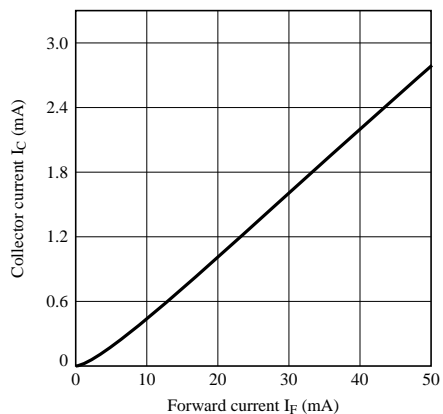


Fig.6 Collector Current vs. Collector-emitter Voltage

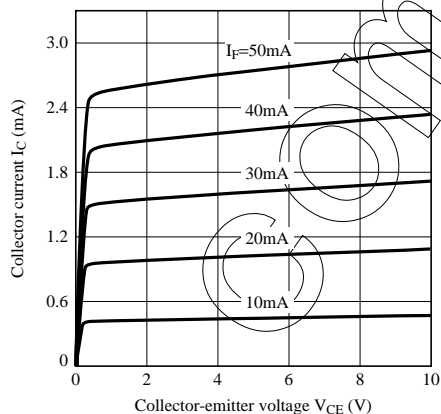


Fig.7 Relative Collector Current vs. Ambient Temperature

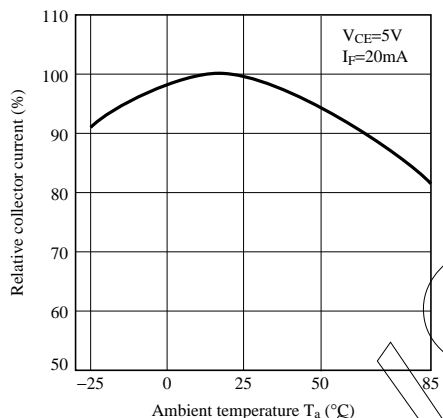


Fig.8 Collector Dark Current vs. Ambient Temperature

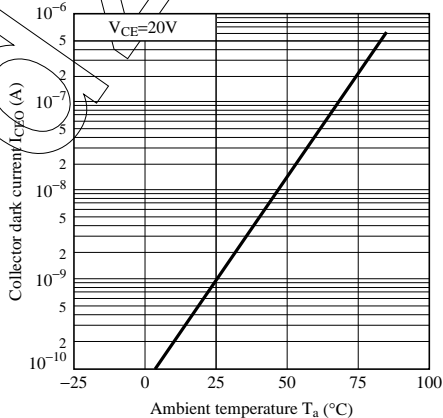


Fig.9 Collector - emitter Saturation Voltage vs. Ambient Temperature

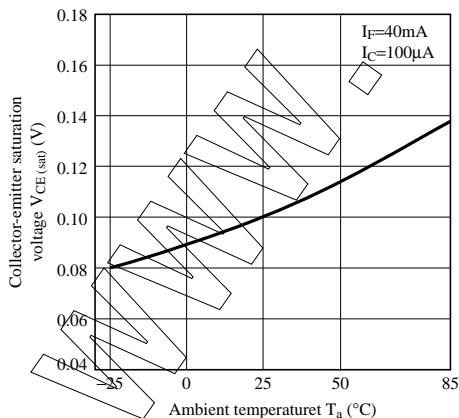


Fig.10 Response Time vs. Load Resistance

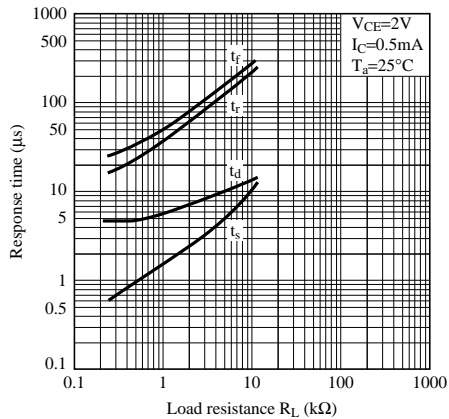


Fig.11 Test Circuit For Response Time

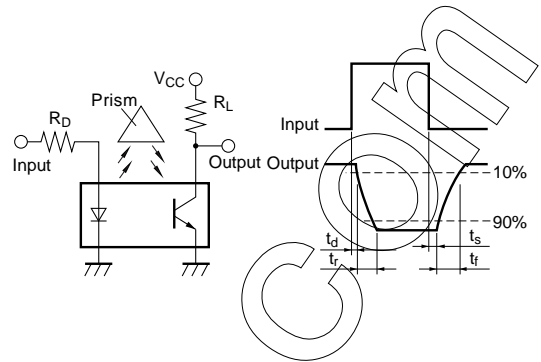


Fig.12 Relative Collector Current vs. Distance Between Sensor and Rectangle Prism

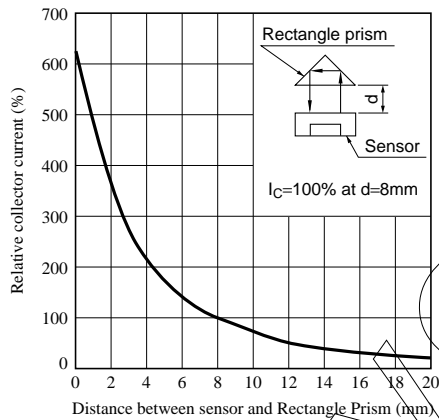


Fig.13 Measuring Configuration of Collector Current

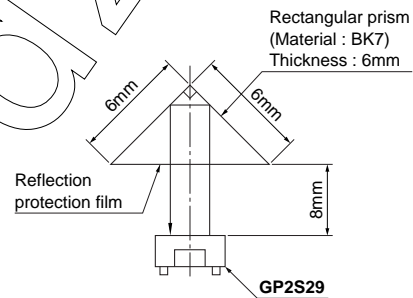


Fig.14 Voltage Gain vs Frequency

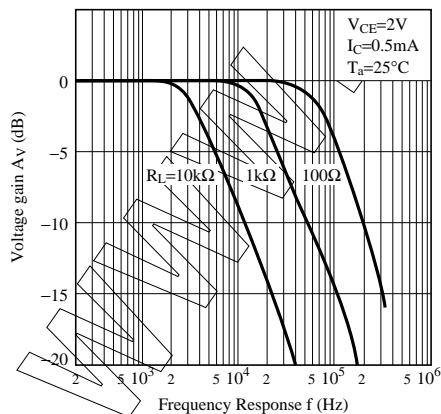
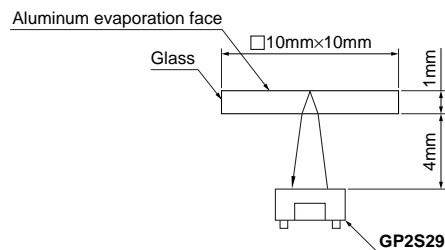


Fig.15 Measuring Configuration of Leak Current



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